

EAST Search History

EAST Search History (Prior Art)

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S49	4	US-6306680-\$.DID. OR US-20020182771-\$.DID.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/06 10:55
S50	1	interposer with interposer adj base with silicon and post adj electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/19 17:42
S51	1	interposer adj base with silicon and post adj electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/19 17:43
S52	1	interposer with silicon and post adj electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/19 17:43
S53	6	interposer with silicon and (post columnar) adj electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/19 17:43
S54	1	interposer with silicon with base and (post columnar) adj electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/19 17:44
S55	6	interposer with silicon and (post cylind\$6 columnar) adj electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/19 17:47

S56	392	interposer with silicon and electrode	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/19 17:48
S57	134	interposer with silicon and electrode and @ay<="2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/19 17:48
S58	6	interposer with silicon and electrode with (cylind\$6 post columnar) and @ay<="2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/19 17:48
S59	0	interposer with silicon and (element chip die) with silicon and electrode and (first and second) adj insulat \$3@ay<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/19 18:20
S60	26100263	interposer with silicon and (element chip die) with silicon and electrode and (first and second) adj insulat \$3 @ay<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/19 18:20
S61	13	interposer with silicon and (element chip die) with silicon and electrode and (first and second) adj insulat \$3 and @ay<"2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/19 18:20
S62	4	US-6306680-\$.DID. OR US-20020182771-\$. DID.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/19 18:30
S63	1	small adj base adj surface adj join\$4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/21 10:53

S64	6	(substrate interposer) with chip with (first and second) adj insulat \$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/21 10:58
S65	0	(substrate interposer) with chip with silcon with (silicon adj (oxide dioxide) "SiO" "SiO. sub.2")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/21 11:01
S66	0	(substrate interposer) with chip with silicon and (silicon adj (oxide dioxide) "SiO" "SiO. sub.2")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/21 11:01
S67	87	(substrate interposer) with chip with silicon and (silicon adj (oxide dioxide) "SiO" "SiO. sub.2")	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/21 11:02
S68	38	(substrate interposer) with chip with silicon and (silicon adj (oxide dioxide) "SiO" "SiO. sub.2") and @ay<="2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/21 11:02
S69	2	(substrate interposer) with chip with silicon and polyimide and @ay<="2003"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2009/10/21 11:27

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